TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOSIV)

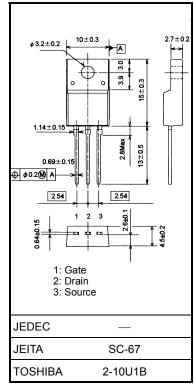
2SK4013

Switching Regulator Applications

- Low drain-source ON resistance: $RDS(ON) = 1.35 \Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 5.0 \text{ S}$ (typ.)
- Low leakage current: $I_{DSS} = 100 \ \mu A (max) (V_{DS} = 640 \ V)$
- Enhancement-model: $V_{th} = 2.0 \sim 4.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ID} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteristics			Symbol	Rating	Unit	
Drain-source voltage			V _{DSS}	800	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)			V _{DGR}	800	V	
Gate-source voltage			V _{GSS}	±30	V	
Drain current	DC	(Note 1)	I _D	6	А	
	Pulse	(Note 1)	I _{DP}	18	A	
Drain power dissipation (Tc = 25° C)			PD	45	W	
Single pulse avalanche energy (Note 2)			E _{AR}	317	mJ	
Avalanche current			I _{AR}	6	А	
Repetitive avalanche energy (Note 3)			E _{AR}	4.5	mJ	
Channel temperature			T _{ch}	150	°C	
Storage temperature range			T _{stg}	-55~150	°C	



Weight: 1.7 g (typ.)

Thermal Characteristics

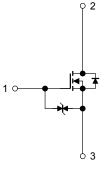
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.78	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	62.5	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: $V_{DD} = 90 \text{ V}, \text{ } T_{ch} = 25^{\circ}\text{C} \text{ (initial)}, \text{ } L = 14.5 \text{ mH}, \text{ } R_{G} = 25 \Omega, \text{ } I_{AR} = 6 \text{ A}$

Note 3: Repetitive rating; pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device. Please handle with caution.



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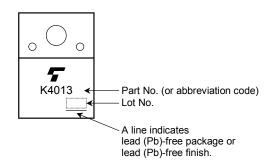
Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS}=\pm 25~V,~V_{DS}=0~V$	_		±10	μA
Drain-source brea	akdown voltage	V (BR) GSS	$I_G=\pm 10~\mu A,~V_{DS}=0~V$	±30			V
Drain cut-OFF cu	rrent	I _{DSS}	$V_{DS} = 640 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			100	μA
Drain-source brea	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	800	_	_	V
Gate threshold vo	oltage	V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	2.0		4.0	V
Drain-source ON resistance		R _{DS (ON)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 3 \text{ A}$		1.35	1.7	Ω
Forward transfer admittance		Y _{fs}	$V_{DS} = 20 \text{ V}, \text{ I}_{D} = 3 \text{ A}$	2.5	5.0		S
Input capacitance		C _{iss}			1400		pF
Reverse transfer capacitance		C _{rss}	V_{DS} = 25 V, V_{GS} = 0 V, f = 1 MHz	_	30		
Output capacitance		C _{oss}			130		
Switching time	Rise time	tr		_	25	_	- ns
	Turn-ON time	t _{on}	₀∨┛└╠╋┱│	_	80	_	
	Fall time	t _f	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	_	65	_	
	Turn-OFF time	t _{off}		_	220		
Total gate charge (gate-source plus gate-drain)		Qg			45	_	nC
Gate-source charge		Q _{gs}	$V_{DD} \simeq 400 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 6 \text{ A}$	_	25		
Gate-drain ("miller") charge		Q _{gd}		_	20		

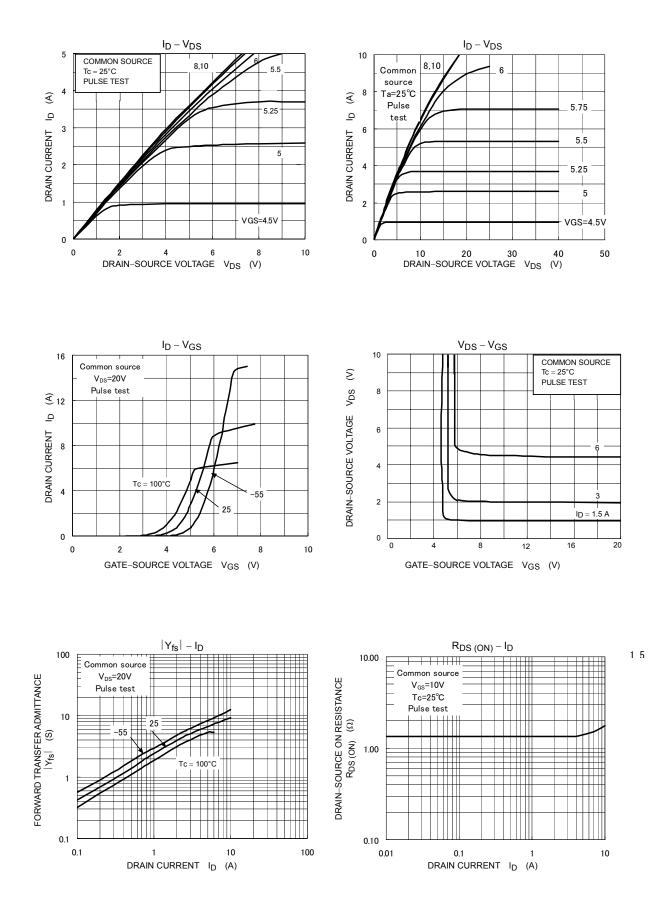
Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	6	А
Pulse drain reverse current (Note 1)	I _{DRP}	—	_	_	18	А
Forward voltage (diode)	V _{DSF}	$I_{DR} = 6 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 6 \text{ A}, V_{GS} = 0 \text{ V},$	_	1100	_	ns
Reverse recovery charge	Q _{rr}	dI _{DR} /dt = 100 A/μs	_	10	_	μC

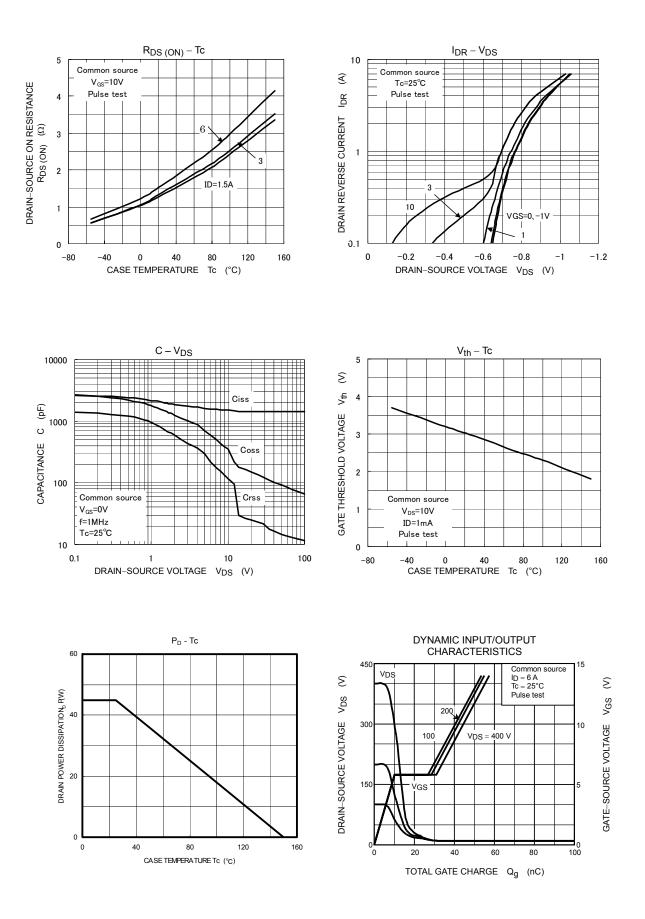
Marking

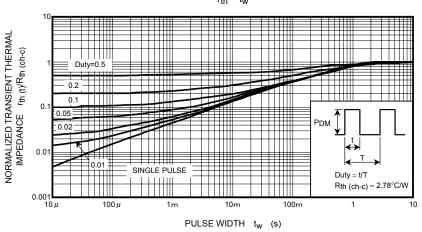


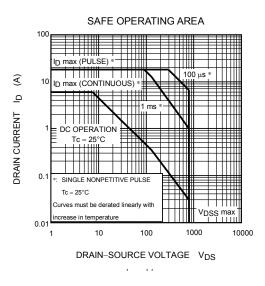
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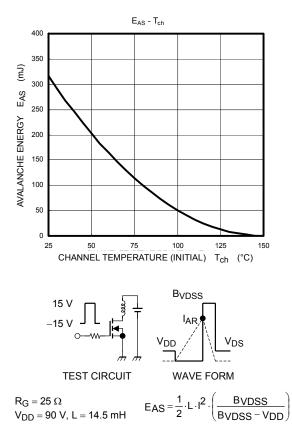


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